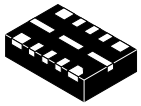
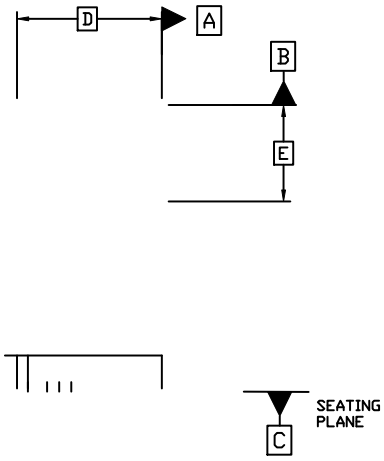


SCALE 4:1

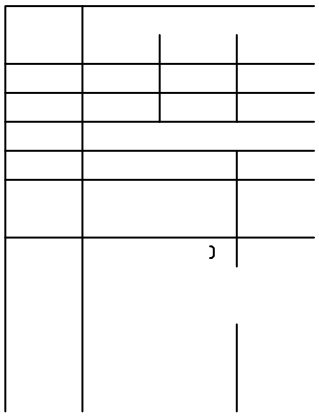
WQFN12 3.0x2.0, 0.5P
CASE 510BM
ISSUE C

DATE 09 DEC 2019



SIONING AND TOLERANCING PER ASME Y14.5M, 2009.

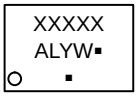
3. DIMENSION b AND b1 APPLY TO THE PLATED TERMINALS AND ARE MEASU



PACKAGE
OUTLINE

RECOMMENDED
MOUNTING FOOTPRINT

GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.